

精材科技股份有限公司



XinTec Inc.

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1. Package Dimensions :

	Symbol	Nominal	Min.	Max.
			μm	
Package Body Dimension X	A	3430	3405	3455
Package Body Dimension Y	B	3950	3925	3975
Package Height	C	740	685	800
Ball Height	C1	95	70	120
Package Body Thickness	C2	645	600	690
Thickness of Glass surface to wafer	C3	405	385	425
Ball Diameter	D	200	170	230
Total Pin Count	N	28		
Pin Count X axis	N1	5		
Pin Count Y axis	N2	6		
Pins Pitch X axis	J1	500		
Pins Pitch Y axis	J2	500		
Edge to Pin Center Distance along X	S1	715	685	745
Edge to Pin Center Distance along Y	S2	725	695	755
Edge to Optical Center Distance along X	E	1720.0	1695.0	1745.0
Edge to Optical Center Distance along Y	F	1883.0	1858.0	1908.0

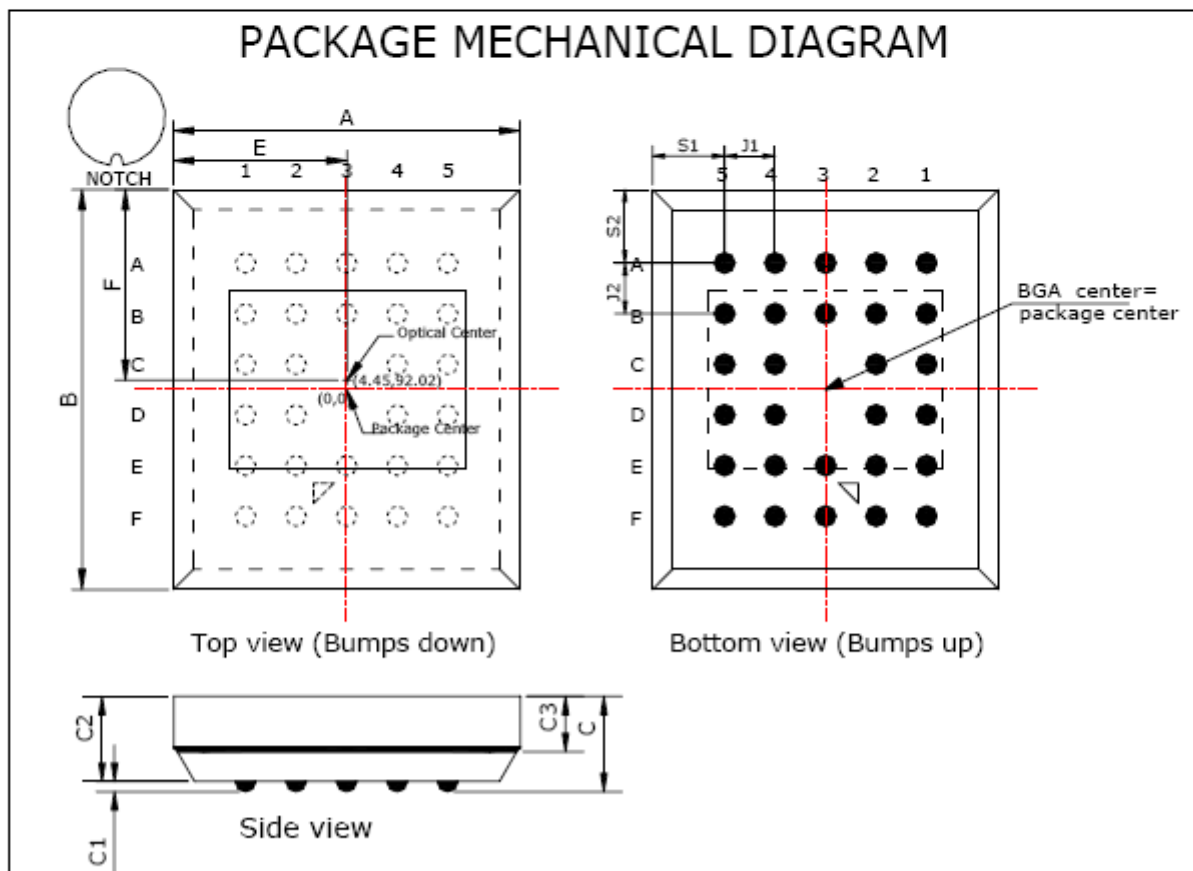


Figure 1.

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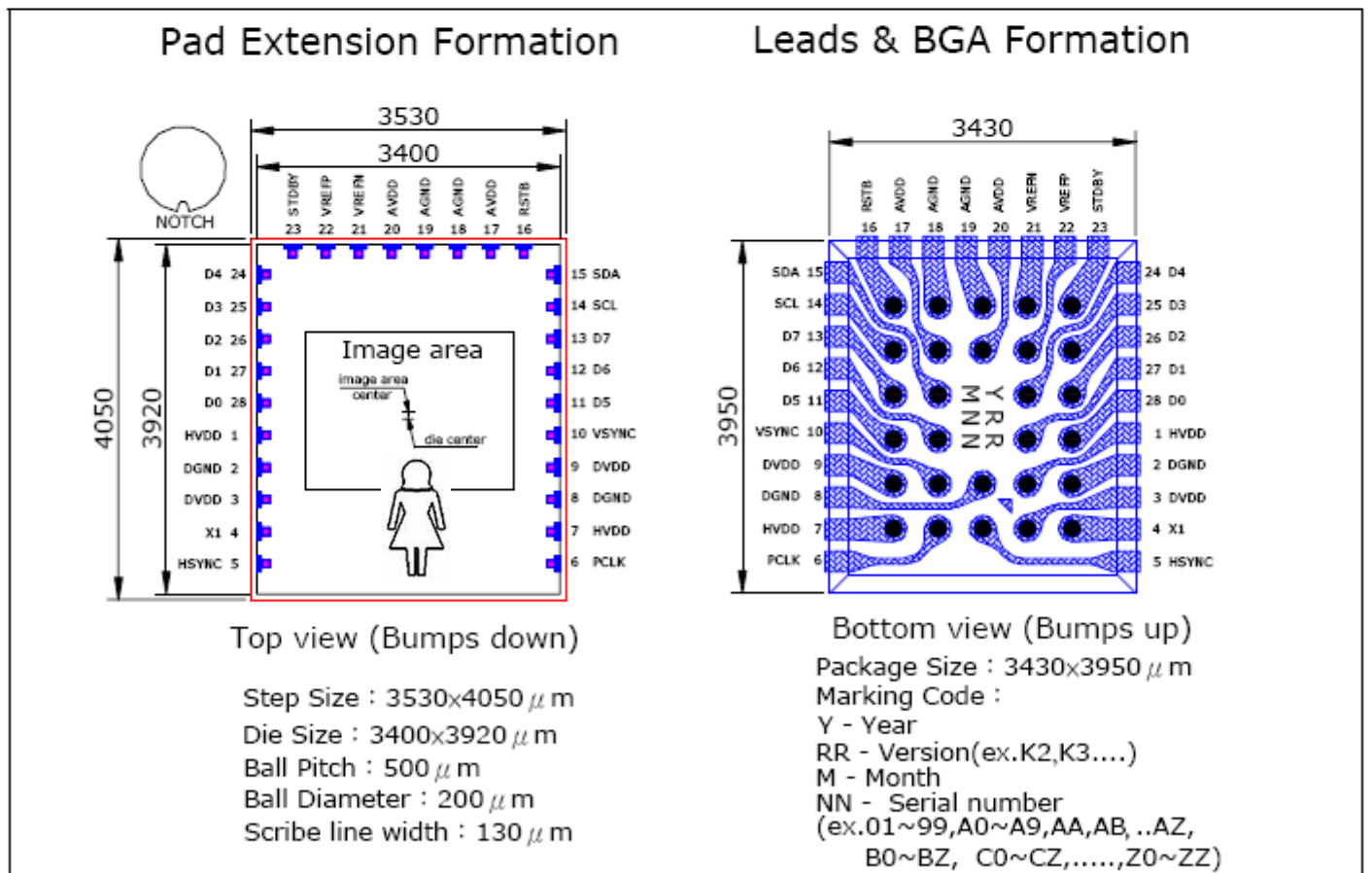


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2. Ball Matrix Table (see Fig. 1 Top View)

	1	2	3	4	5
A	23. STDBY	21. VREFN	19. AGND	18. AGND	16. RSTB
B	25. D3	22. VREFP	20. AVDD	17. AVDD	14. SCL
C	26. D2	24. D4		15. SDA	13. D7
D	28. D0	27. D1		12. D6	11. D5
E	2. DGND	1. HVDD	8. DGND	10. VSYNC	9. DVDD
F	4. X1	3. DVDD	5. HSYNC	6. PCLK	7. HVDD



※ Image direction: without lens

Figure 2